

# 3-Phase Synchronous-Rectified Buck Controller for Mobile GPU Power

### **General Description**

The uP1642P is a 3/2/1-phase synchronous-rectified buck controller specifically designed to work with 4.5V ~ 26V input voltage and deliver high quality output voltage for high-performance graphic processor power.

The uP1642P adopts proprietary RCOT™ technology, providing flexible selection of output LC filter and excellent transient response to load and line change.

The uP1642P supports NVIDIA Open Voltage Regulator-2 and 2+1 with PWMVID feature. The PWMVID input is buffered and filtered to generate accurate reference voltage, and the output voltage is precisely regulated to the reference input.

The uP1642P integrates two bootstrapped MOSFET gate drivers and one PWM output achieving optimal balance between cost and flexibility. The uP1642P uses MOSFET  $R_{DS(ON)}$  current sensing for channel current balance.

Other features include accurate and reliable short-circuit protection, adjustable on-time setting, power saving control input, and a delayed power good output. This part is available in VQFN4x4 - 24L package.

### Ordering Information

Order Number	Package Type	Top Marking
uP1642PQAG	VQFN4x4-24L	uP1642P

Note: uPI products are compatible with the current IPC/ JEDEC J-STD-020 requirement. They are halogen-free, RoHS compliant and 100% matte tin (Sn) plating that are suitable for use in SnPb or Pb-free soldering processes.

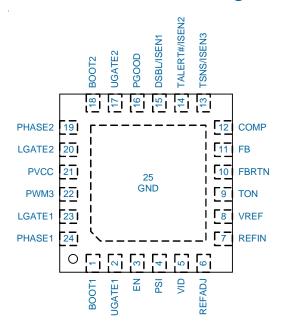
# Applications

- Middle-High End GPU Core Power
- □ High End Desktop PC Memory Core Power
- Low Output Voltage, High Power Density DC-DC Converters
- Voltage Regulator Modules

### Features

- Support NVIDIA's Open VReg Type-2 and 2+1 PWMVID Technology
- Wide Input Voltage Range 4.5V ~ 26V
- Robust Constant On-Time Control
- □ 3/2/1 Phase Operation
- Two Integrated MOSFET Drivers with Shoot-Through Protection and Internal Bootstrap Switch
- Adjustable Current Balancing by R<sub>DS(ON)</sub> Current Sensing
- Adjustable Operation Frequency from 200kHz to 1MHz
- External Compensation
- Support NVIDIA's PWMVID Function
- Dynamic Output Voltage Adjustment
- Temperature Sensing and Thermal Alert
- Power Good Indication
- Over Voltage Protection
- Under Voltage Protection
- Short Circuit Protection
- Over Temperature Protection
- RoHS Compliant and Halogen Free

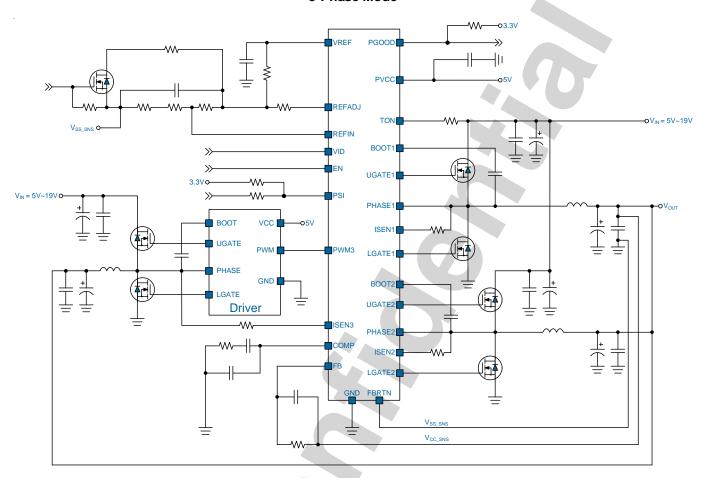
**Pin Configuration** 





# Typical Application Circuit

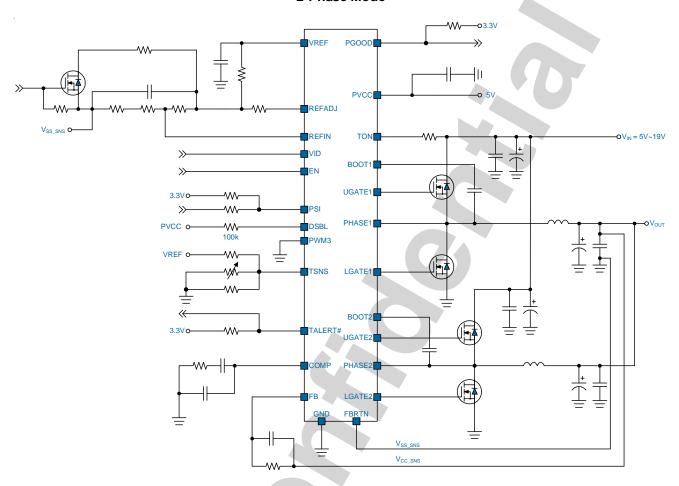
### 3-Phase Mode





# **Typical Application Circuit**

### 2-Phase Mode



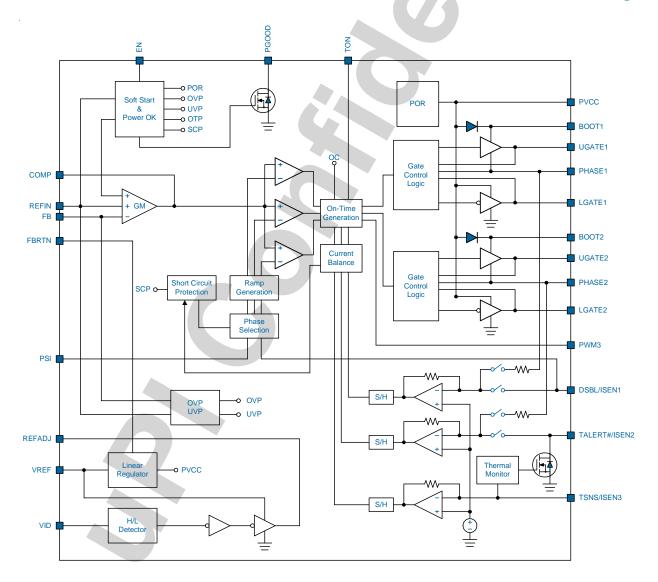


No.	Name	Pin Function
1	BOOT1	<b>BOOT for Phase 1.</b> Connect a capacitor form this pin to PHASE1 to form a bootstrap circuit for upper gate driver of the phase 1.
2	UGATE1	Upper Gate Driver for Phase 1. Connect this pin to the gate of phase 1 upper MOSFET.
3	EN	Enable. Chip enable.
4	PSI	Power Saving Input. An input pin receiving power saving control signal from GPU.
5	VID	VID. PWMVID input pin.
6	REFADJ	Reference Adjustment. PWMVID output pin. Connect this pin with an RC integrator to generate REFIN voltage.
7	REFIN	<b>Reference Input.</b> Connect this pin to an external reference voltage through a resistor or connect to the output of the REFADJ circuit. Pulling low this pin down to 0.15V shuts down the uP1642P.
8	VREF	Reference Voltage. 2V LDO voltage output pin. Connect an at least 1uF decoupling capacitor between this pin and GND.
9	TON	On-time Setting Pin. Connect a resistor from this pin to VIN to set the on-time of the upper MOSFET.
10	FBRTN	Return for the Reference Circuit. Connect this pin to the ground point where output voltage is to be regulated.
11	FB	Feedback Pin. This pin is the inverting input of the error amplifier.
12	COMP	Compensation Output. This pin is the output of the error amplifier.
13	TSNS/ISEN3	Thermal monitor (2-phase mode) or ISEN3 (3-phase mode). As thermal monitor pin, connect this pin to an NTC network near power stage to monitor thermal condition of the system. As ISEN3 pin, connect this pin to the phase node of phase 3 with a resistor to sense phase 3 output current.
14	TALERT#/IS- EN2	<b>TALERT# (2-phase mode) or ISEN2 (3-phase mode).</b> As TALERT# pin, connect this pin to a voltage source with a pull-up resistor. TALERT# is an active low, open-drain output to indicate high temperature condition. As ISEN2 pin, connect this pin to the PHASE2 pin with a resistor to sense phase 3 output current.
15	DSBL/ISEN1	<b>DSBL (2-phase mode) or ISEN1 (3-phase mode). If</b> in 2-phase mode, this pin should be connected to PVCC. If in 3-phase mode, connect this pin to the PHASE1 pin with a resistor to sense phase 1 output current.
16	PGOOD	<b>Power Good Indication.</b> Connect this pin to a voltage source with a pull-up resistor. Opendrain structure.
17	UGATE2	Upper Gate Driver for Phase 2. Connect this pin to the gate of phase 2 upper MOSFET.
18	BOOT2	<b>BOOT</b> for Phase 2. Connect a capacitor form this pin to PHASE2 to form a bootstrap circuit for upper gate driver of the phase 2.
19	PHASE2	<b>Phase Pin for Phase 2.</b> This pin is the return path of upper gate driver for phase 2. Connect a capacitor from this pin to BOOT2 to form a bootstrap circuit for upper gate driver of the phase2.
20	LGATE2	Lower Gate Driver for Phase 2. Connect this pin to the gate of phase 2 lower MOSFET.



No.	Name	Pin Function
21	PVCC	<b>Supply Input for the IC.</b> Voltage power supply of the IC. Connect this pin to a 5V supply and decouple using at least a 0.1uF ceramic capacitor.
22	PWM3	<b>PWM Output of Phase 3</b> . Connect this pin to the PWM input pin of the companion gate driver. Connect this pin to GND when maximum 2 phase operation.
23	LGATE1	Lower Gate Driver for Phase 1. Connect this pin to the gate of phase 1 lower MOSFET.
24	PHASE1	Phase Pin for Phase 1. This pin is the return path of upper gate driver for phase 1. Connect a capacitor from this pin to BOOT1 to form a bootstrap circuit for upper gate driver of the phase 1.
25	Exposed Pad	<b>Ground.</b> Tie this pin to ground island/plane through the lowest impedance connection available.

# Functional Block Diagram





The uP1642P is a 3/2/1-phase synchronous-rectified buck controller specifically designed to work with 4.5V ~ 26V input voltage and deliver high quality output voltage for high-performance graphic processor power.

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The uP1642P supports NVIDIA Open Voltage Regulator-2 and 2+1 with PWMVID feature. The PWMVID input is buffered and filtered to generate accurate reference voltage, and the output voltage is precisely regulated to the reference input.

The uP1642P integrates two bootstrapped MOSFET gate drivers and one PWM output achieving optimal balance between cost and flexibility. The uP1642P uses MOSFET  $R_{\text{DS(ON)}}$  current sensing for channel current balance.

Other features include accurate and reliable short-circuit protection, adjustable on-time setting, power saving control input, and a power good output. This part is available in VQFN4x4 - 24L package.

### **Supply Input and Power On Reset**

The uP1642P receives supply input from PVCC pin to provide current to gate drivers and internal control circuit. PVCC is continuously monitored for power on reset. The POR level is typical 4.1V at rising. The TON pin voltage is used for ontime calculation and should be connected to the supply input of power stage.

The uP1642P integrates floating MOSFET gate driver that are powered from the PVCC pin. A bootstrap switch is embedded to facilitates PCB design and reduce the total BOM cost. No external Schottky diode is required in real applications. An external Schottky diode with lower voltage drop can improve the power conversion efficiency.

### **Phase Number of Operation (Hard-wire Programming)**

The uP1642P supports 3/2/1 phase operation. The maximum phase number of operation is determined by checking the DSBL/ISEN1 status when POR. If DSBL/ISEN1 is connected to a voltage source higher than (PVCC-1V) during POR, the uP1642P enters 2-phase operation. Tie DSBL/ISEN1 by a  $100 k\Omega$  resistor to PVCC for maximum 2-phase configuration where phase3 is disabled. In 2-phase operation, pin 13 is auto-switched to TSNS pin, and pin 14 is auto-switched to TALERT# pin. Once selected, the maximum phase number of operation is latched and can only be changed at the next POR.

### **Constant On-Time Setting**

The uP1642P adopts a compensated constant-on-time control scheme. A resistor  $R_{\text{TON}}$  connected to TON pin programs the constant on time according to the equation:

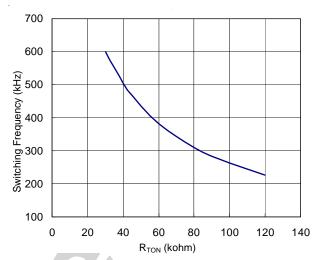


Figure 1. Switching Frequency vs. R<sub>TON</sub>

$$T_{ON} = 300 \times \frac{R_{TON} + 18k\Omega}{9k\Omega} \times \frac{V_{REFIN}}{V_{IN}}$$
 (ns)

where  $R_{\scriptscriptstyle TON}$  is in  $k\Omega,\,V_{\scriptscriptstyle IN}$  is the supply input voltage and  $V_{\scriptscriptstyle REFIN}$  is the input voltage at the REFIN pin.

### **Voltage Control Loop and PWMVID Function**

Figure 2 illustrates the voltage control loop of the uP1642P. FB and REFIN are negative and positive inputs of the Error Amplifier respectively. The Error Amplifier modulates the COMP voltage  $V_{\text{COMP}}$  of buck converter to force FB voltage  $V_{\text{FR}}$  follows  $V_{\text{REFIN}}$ .

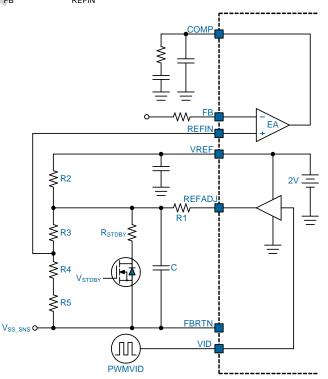


Figure 2. Voltage Control Loop



The PWMVID signal from GPU is applied to the VID pin, which is the input pin of the internal buffer. This buffer plays the role of level shifting, and the output of this buffer is injected into the external RC integrator to generate REFIN voltage, which can be calculated as:

$$V_{REFIN} =$$

$$V_{VREF} \times D \times \frac{R2/(R3 + R4 + R5)}{R1 + R2/(R3 + R4 + R5)} \times \frac{R4 + R5}{R3 + R4 + R5} +$$

$$V_{VREF} \times \frac{R1/(R3 + R4 + R5)}{R2 + R1/(R3 + R4 + R5)} \times \frac{R4 + R5}{R3 + R4 + R5}$$

where  $V_{\text{REFIN,DC}}$  is the DC voltage of REFIN,  $V_{\text{VREF}}$  is the voltage of VREF (typically 2V), and D is the duty cycle of PWMVID input.

### **Boot Voltage and Standby Mode**

The new generation PWMVID structure includes two operation modes other than normal operation: boot mode and standby mode. During boot mode, the GPU stops sending PWMVID signal and the input of the PWMVID buffer is floating. The REFADJ pin enters high impedance state after the VID pin enters tri-state region, and the REFIN voltage can then be calculated as:

$$V_{REFIN,BOOT} = V_{VREF} \times \frac{R4 + R5}{R2 + R3 + R4 + R5}$$

During standby mode, other than GPU stopping the PWMVID transaction, an external system standby signal additionally controls the entry of standby mode. An additional external switch should be connected in parallel with the original PWMVID resistors as shown in Figure 3 to generate the standby mode voltage:

# $V_{REFIN,STDBY} = V_{VREF} \times \frac{(R3 + R4 + R5) /\!/ R_{STDBY}}{R2 + (R3 + R4 + R5) /\!/ R_{STDBY}} \times \frac{R4 + R5}{R3 + R4 + R5}$ $\frac{REFIN}{R3} \times \frac{R}{R3} \times \frac{R}{R} \times \frac{R$

Figure 3. Standby Mode Configuration

### **Channel Current Balance**

The uP1642P senses phase currents for current balance by the means of on-resistance of power stage low-side MOSFET as shown in Figure 4.

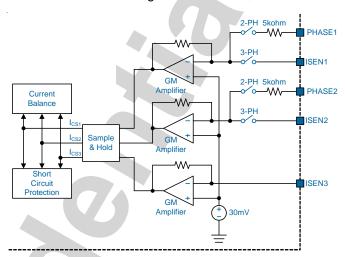


Figure 4. R<sub>DS(ON)</sub> Current Sensing Scheme

The GM amplifier senses the voltage drop across the lowside MOSFET and converts it into current signal each time it turns on. The sampled and held current is expressed as:

$$I_{CSX} = \frac{\left(I_{LX} \times R_{DS(ON)} + V_{DC}\right)}{R_{ISENX}}$$

where  $\rm I_{LX}$  is the phase X current in Ampere,  $\rm R_{\rm DS(ON)}$  is the on-resistance of low-side MOSFET of the power stage in  $\rm m\Omega$ ,  $\rm V_{\rm DC}$  is an internal 30mV voltage source, and  $\rm R_{\rm ISENX}$  is the external sensing resistor connected at ISENx pins. In maximum 3-phase operation, the  $\rm R_{\rm ISENX}$  is determined by external ISEN resistors. In maximum 2-phase operation, the ISEN pins are auto-switched into multi-function pins (TSNS and TALERT#), and the current sense resistors are also auto-switched into the internal  $\rm R_{\rm ISEN}$  resistors. The resistance of the internal  $\rm R_{\rm ISEN}$  resistors during maximum 2-phase operation is  $\rm 5k\Omega$ . In this current sense mechanism, the valley of the inductor current is sampled and held. Therefore, the equivalent sensed current can be described by the following equation:

$$I_{LX\_SH} = I_{LX\_AVG} - \frac{1}{2} \times \Delta I_{LX}$$

The sensed current  $I_{LX\_SH}$  is mirrored to the current balance circuit, comparing between each other, and generating current adjusting signals for each phase. These current adjusting signals are fed to the on-time circuit of the uP1642P to separately adjust each phase on-time for the purpose of adjusting current balance.

### **Soft-Start and Power Good**

A built-in soft-start is used to prevent surge current from power supply input during turn on. The error amplifier is a three-input device. Reference voltage  $V_{\text{RFFIN}}$  or the internal



soft-start voltage SS whichever is smaller dominates the behavior of the non-inverting inputs of the error amplifier. SS internally ramps up to PVCC with a slew rate determined by  $V_{\text{REFIN}}$  after the soft start cycle is initiated. Accordingly, the output voltage will follow the SS signal and ramp up smoothly to its target level. The output voltage ramp-up time is typically 1.4ms.

### **Power Saving Mode**

The uP1642P provides power saving features for platform designers to program platform specific power saving configuration. There are four operation modes: multi-phase CCM, single-phase USM, single-phase FCCM, and singlephase PSM. The uP1642P switches between these four operation modes according to the input voltage level of the PSI pin. Figure 5 shows typical PSI application circuit, and table 1 shows recommended PSI setting voltage level of four operation modes. In single-phase operation, the uP1642P auto-selects phase 1 to be the operating phase. In PSM, the uP1642P automatically reduces switching frequency at light load to maintain high efficiency. As the load current decreases, the rectifying MOSFET is turned off when zero inductor current is detected, and the converter runs in discontinuous conduction mode. In USM, the operation of the converter is also a discontinuous conduction. mode similar to PSM, and additionally the USM control circuit monitors both high-side and low-side MOSFETs and force to change into the ON state to avoid the switching frequency falling within audible region.

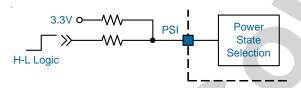


Figure 5. PSI application circuit

Operation Mode	Recommended Voltage Setting at PSI
Multi-Phase CCM	3.3V
Single-Phase USM	2V
Single-Phase FCCM	1.2V
Single-Phase PSM	GND

Table 1. Recommended PSI Setting

### **Thermal Alert Function**

By pulling pin 15 to PVCC, the uP1642P operates in 2-phase mode and the thermal alert function is enabled on pin 14 (TALERT#) and pin 13 (TSNS). Figure 6 shows typical settings of the thermal alert function. A resistive voltage divider

with NTC linearization network forms a typical TSNS setting. The pull-up voltage of the TSNS pin must be the VREF (2V) voltage generated by the uP1642P to guarantee the accuracy of the thermal alert function. When the sensed temperature rises, the TSNS voltage falls along with the resistance change of the NTC. When the TSNS voltage falls below 35% of VREF, the TALERT# is asserted (low active). There is a 7.5% hysteresis of TSNS voltage to prevent false trigger of TALERT#.

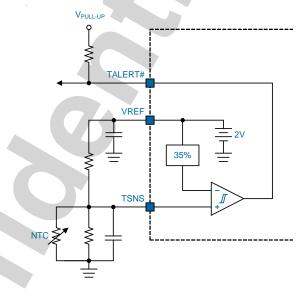


Figure 6. Thermal Alert Function

### **Short Circuit Protection (SCP)**

The uP1642P adopts per-phase current short circuit protection function to avoid catastrophic damage to power stage components. The uP1642P monitors the sensed current at ISENx pins and if the sensed  $I_{\rm csx}$  of any phase exceeds 37.5uA, the short circuit protection activates. According the mentioned current sense equation, the short circuit protection equation can be written as:

$$I_{MAX,per-phase} = \frac{37.5uA \times R_{ISENX} - V_{DC}}{R_{DS(ON)}}$$

Where 37.5uA is the internal SCP threshold current,  $R_{\rm ISENX}$  is the external sensing resistor connected at ISENx pins,  $V_{\rm DC}$  is an internal 30mV voltage source, and  $R_{\rm DS(ON)}$  is the on-resistance of the low-side MOSFET of the power stage in m $\Omega$ . Since the SCP mechanism detects per-phase current for SCP triggering, the total SCP threshold can be calculated as:

$$I_{MAX,total} = P \times \frac{\left(37.5 uA \times R_{ISENX} - V_{DC}\right)}{R_{DS(ON)}}$$

where P denotes operating phase number.



In maximum 3-phase operation, the  $R_{\rm ISENX}$  is determined by external ISEN resistors. In maximum 2-phase operation, the ISEN pins are auto-switched into multi-function pins (TSNS and TALERT#), and the current sense resistors are also auto-switched into the internal  $R_{\rm ISEN}$  resistors. The resistance of the internal  $R_{\rm ISEN}$  resistors during maximum 2-phase operation is  $5k\Omega$ .

After per-phase current exceeds SCP threshold and sustained 6us, the short circuit protection is triggered and shuts down the uP1642P and turns off all high-side and low-side MOSFETs if any phase's current exceeds  $I_{\text{MAX}}$ , and this latched-off protection can only be reset by PVCC re-POR or EN restart.

### Over Voltage Protection (OVP)

The OVP is triggered if  $V_{FB} > 1.4 \text{xV}_{REFIN}$  sustained 6us. When OVP is activated, the uP1642P turns on all low-side MOSFET and turns off all high-side MOSFET. The over voltage protection is a latch-off function and can only be reset by PVCC re-POR or EN restart.

### **Under Voltage Protection (UVP)**

The under voltage protection is triggered if  $V_{\rm FB} < 0.5 {\rm xV}_{\rm REFIN}$  sustained 10us. When UVP is activated, the uP1642P turns off all high-side and low-side MOSFET. The under voltage protection is a latch-off function and can only be reset by PVCC re-POR or EN restart.

### **Over Temperature Protection (OTP)**

The uP1642P monitors the temperature of itself. If the temperature exceeds typical 150°C, the uP1642P is forced into shutdown mode. The over temperature protection is a latch-off function and can only be reset by PVCC re-POR or EN restart.





$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		Absolute Maximum Rating
BOOTx to PHASEx	(Note 1)	
DC		0.3V to +6.5V
PHASEx to GND         -0.77 to +28V           ∠200ns         -87 to +36V           BOOTx to GND         -0.37 to (V <sub>PVCC</sub> +36V)           ∠200ns         -0.37 to +42V           UGATEx to PHASEx         DC           DC         -0.38 to (BOOTx-PHASEx+0.3V)           ∠200ns         -5V to (BOOTx-PHASEx+0.3V)           LGATEx to GND         -5V to (V <sub>PVCC</sub> +0.3V)           DC         -0.38 to (V <sub>PVCC</sub> +0.3V)           ∠200ns         -5V to (V <sub>PVCC</sub> +0.3V)           Other Pins         -5V to (V <sub>PVCC</sub> +0.3V)           Storage Temperature Range         -65°C to +150°C           Junction Temperature         150°C           Lead Temperature (Soldering, 10 sec)         260°C           ESD Rating (Note 2)         150°C           HBM (Human Body Mode)         2kV           MM (Machine Mode)         2kV           Thermal Information           Package Thermal Resistance (Note 3)         VQFN4x4 - 24L θ <sub>JG</sub> 40°C/W           Power Dissipation, P <sub>D</sub> @ T <sub>A</sub> = 25°C         2.5W           Recommended Operation Conditions           (Note 4)         Qperating Junction Temperature Range         -40°C to +125°C           Operating Ambient Temperature Range         -40°C to +85°C		
DC		
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$\begin{array}{c} \text{UGATEx to PHASEx} \\ \text{DC} & -0.3V \text{ to (BOOTx-PHASEx+0.3V)} \\ < 200 \text{ns} & -5V \text{ to (BOOTx-PHASEx+0.3V)} \\ \text{LGATEx to GND} \\ \text{DC} & -0.3V \text{ to (V}_{\text{PVCC}} + 0.3V)} \\ < 200 \text{ns} & -5V \text{ to (V}_{\text{PVCC}} + 0.3V)} \\ \text{Other Pins} & -5V \text{ to (V}_{\text{PVCC}} + 0.3V)} \\ \text{Storage Temperature Range} & -65^{\circ}\text{C to +150}^{\circ}\text{C}} \\ \text{Junction Temperature} & 150^{\circ}\text{C}} \\ \text{Lead Temperature (Soldering, 10 sec)} & -260^{\circ}\text{C}} \\ \text{ESD Rating (Note 2)} \\ \text{HBM (Human Body Mode)} & -2kV \\ \text{MM (Machine Mode)} & -200V \\ \hline \\ \textbf{Package Thermal Resistance (Note 3)} \\ \text{VQFN4x4 - 24L $\theta_{\text{JC}}$} & -40^{\circ}\text{C to +150}^{\circ}\text{C}} \\ \text{Power Dissipation, $P_{\text{D}} \otimes T_{\text{A}} = 25^{\circ}\text{C}} \\ \text{VQFN4x4 - 24L $\theta_{\text{JC}}$} & -2.5W \\ \hline \\ \textbf{Recommended Operation Conditions} \\ \text{(Note 4)} \\ \text{Operating Junction Temperature Range} & -40^{\circ}\text{C to +185}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Information} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Information} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \textbf{Operating Information} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \textbf{Operating Information} \\ \textbf$		0.3\/to/\/ 1.36\/\
$\begin{array}{c} \text{UGATEx to PHASEx} \\ \text{DC} & -0.3V \text{ to (BOOTx-PHASEx+0.3V)} \\ < 200 \text{ns} & -5V \text{ to (BOOTx-PHASEx+0.3V)} \\ \text{LGATEx to GND} \\ \text{DC} & -0.3V \text{ to (V}_{\text{PVCC}} + 0.3V)} \\ < 200 \text{ns} & -5V \text{ to (V}_{\text{PVCC}} + 0.3V)} \\ \text{Other Pins} & -5V \text{ to (V}_{\text{PVCC}} + 0.3V)} \\ \text{Storage Temperature Range} & -65^{\circ}\text{C to +150}^{\circ}\text{C}} \\ \text{Junction Temperature} & 150^{\circ}\text{C}} \\ \text{Lead Temperature (Soldering, 10 sec)} & -260^{\circ}\text{C}} \\ \text{ESD Rating (Note 2)} \\ \text{HBM (Human Body Mode)} & -2kV \\ \text{MM (Machine Mode)} & -200V \\ \hline \\ \textbf{Package Thermal Resistance (Note 3)} \\ \text{VQFN4x4 - 24L $\theta_{\text{JC}}$} & -40^{\circ}\text{C to +150}^{\circ}\text{C}} \\ \text{Power Dissipation, $P_{\text{D}} \otimes T_{\text{A}} = 25^{\circ}\text{C}} \\ \text{VQFN4x4 - 24L $\theta_{\text{JC}}$} & -2.5W \\ \hline \\ \textbf{Recommended Operation Conditions} \\ \text{(Note 4)} \\ \text{Operating Junction Temperature Range} & -40^{\circ}\text{C to +185}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Information} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Ambient Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \text{Operating Information} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \textbf{Operating Information} \\ \textbf{Operating Information Temperature Range} & -40^{\circ}\text{C to +85}^{\circ}\text{C}} \\ \textbf{Operating Information} \\ \textbf$	200ns	
$\begin{array}{c} DC \\ < 200 \text{ns} \\ < 200 \text{ns} \\ \\ -5 \text{V to (BOOTx-PHASEx+0.3V)} \\ \\ LGATEx to GND \\ DC \\ < 200 \text{ns} \\ & -5 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}) \\ < 2200 \text{ns} \\ & -5 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}) \\ \\ \text{Other Pins} \\ & -5 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}) \\ \\ \text{Storage Temperature Range} \\ & -65^{\circ}\text{C to +150}^{\circ}\text{C} \\ \\ \text{Junction Temperature} \\ \text{Lead Temperature (Soldering, 10 sec)} \\ \text{ESD Rating (Note 2)} \\ \text{HBM (Human Body Mode)} \\ \text{MM (Machine Mode)} \\ \\ \text{Package Thermal Resistance (Note 3)} \\ \text{VQFN4x4 - 24L} \theta_{\text{JC}} \\ \text{VQFN4x4 - 24L} \theta_{\text{JC}} \\ \text{Power Dissipation, P}_{\text{D}} @ T_{\text{A}} = 25^{\circ}\text{C} \\ \text{VQFN4x4 - 24L} \theta_{\text{JC}} \\ \\ \text{Power Dissipation, P}_{\text{D}} @ T_{\text{A}} = 25^{\circ}\text{C} \\ \text{VQFN4x4 - 24L} \theta_{\text{JC}} \\ \\ \text{Operating Junction Temperature Range} \\ \\ \text{MRCOMMended Operation Conditions} \\ \\ \text{(Note 4)} \\ \text{Operating Junction Temperature Range} \\ \\ \text{-40}^{\circ}\text{C to +125}^{\circ}\text{C} \\ \text{Operating Ambient Temperature Range} \\ \\ \text{-40}^{\circ}\text{C to +85}^{\circ}\text{C} \\ \\ \text{Operating Ambient Temperature Range} \\ \\ \text{-40}^{\circ}\text{C to +85}^{\circ}\text{C} \\ \\ \text{-20} \\ $		-0.5V tO +42V
$ \begin{array}{c} < 200 \text{ns} & -5 \text{V to (BOOTx-PHASEx+0.3V)} \\ \text{LGATEx to GND} & -0.3 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}} \\ \text{DC} & -0.3 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}} \\ < 200 \text{ns} & -5 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}} \\ \text{Other Pins} & -5 \text{V to (V}_{\text{PVCC}} + 0.3 \text{V}} \\ \text{Storage Temperature Range} & -65^{\circ}\text{C to +150}^{\circ}\text{C} \\ \text{Junction Temperature} & -150^{\circ}\text{C} \\ \text{Lead Temperature (Soldering, 10 sec)} & -260^{\circ}\text{C} \\ \text{ESD Rating (Note 2)} & -260^{\circ}\text{C} \\ \text{ESD Rating (Note 2)} & -260^{\circ}\text{C} \\ \text{MM (Machine Mode)} & -2 \text{kV} \\ \text{MM (Machine Mode)} & -2 \text{kV} \\ \text{MM (Machine Mode)} & -2 \text{kV} \\ \text{VQFN4x4-24L} \theta_{\text{JG}} & -40^{\circ}\text{CM} \\ \text{VQFN4x4-24L} \theta_{\text{JG}} & -40^{\circ}\text{CM} \\ \text{Power Dissipation, P}_{\text{D}} @ T_{\text{A}} = 25^{\circ}\text{C} \\ \text{VQFN4x4-24L} \theta_{\text{JC}} & -2.5 \text{W} \\ \hline & & & & & & & & & & & & & & & & & &$		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	<200ns	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	LOATE 1: OND	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	DC	
$ \begin{array}{c} \text{Other Pins} & -5\text{V to } (\text{V}_{\text{PVCC}} + 0.3\text{V} \\ \text{Storage Temperature Range} & -65^{\circ}\text{C to} + 150^{\circ}\text{C} \\ \text{Junction Temperature} & 150^{\circ}\text{C} \\ \text{Lead Temperature (Soldering, 10 sec)} & 260^{\circ}\text{C} \\ \text{ESD Rating (Note 2)} & +260^{\circ}\text{C} \\ \text{MM (Machine Mode)} & -2k\text{V} \\ \text{MM (Machine Mode)} & -200\text{V} \\ \hline                                  $	<200ns	
Junction Temperature	Other Pins	5V to $(V_{PVCC} + 0.3V)$
Junction Temperature	Storage Temperature Range	
	Junction Temperature	150°C
	Lead Temperature (Soldering, 10 sec)	260°C
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	ESD Rating (Note 2)	
Package Thermal Resistance (Note 3) $\begin{array}{cccccccccccccccccccccccccccccccccccc$	HBM (Human Body Mode)	2kV
Package Thermal Resistance (Note 3) $\begin{array}{cccccccccccccccccccccccccccccccccccc$	MM (Machine Mode)	200V
Package Thermal Resistance (Note 3) $ \begin{array}{ccccccccccccccccccccccccccccccccccc$		The war of Information
$\begin{array}{cccccccccccccccccccccccccccccccccccc$		I nermal information
Power Dissipation, $P_D @ T_A = 25^{\circ}C$ $VQFN4x4 - 24L\theta_{JC}$	Package Thermal Resistance (Note 3)	
Power Dissipation, $P_D @ T_A = 25^{\circ}C$ $VQFN4x4 - 24L\theta_{JC}$	VQFN4x4 - 24L θ <sub>JA</sub>	40°C/W
Power Dissipation, $P_D @ T_A = 25^{\circ}C$ $VQFN4x4 - 24L\theta_{JC}$	VQFN4x4 - 24L $\theta_{JC}^{JA}$	4°C/W
(Note 4) Operating Junction Temperature Range	Power Dissipation P $(\alpha)$ T = 25°C	
(Note 4) Operating Junction Temperature Range	VQFN4x4 - 24L $\theta_{JC}$	2.5W
(Note 4) Operating Junction Temperature Range		Pasammandad Operation Conditions
Operating Junction Temperature Range		Recommended Operation Conditions
Operating Ambient Temperature Range	Operating Junction Temperature Range	
Input Voltage, V <sub>IN</sub> 3V to 26V		
	Input Voltage, V	3V to 26V



# Electrical Characteristics

(PVCC = 5V, $T_A = 25^{\circ}$ C, unless otherwis	1					
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Supply Input						
Supply Current	I <sub>PVCC</sub>	$V_{\text{REFIN}} = 0.9 \text{V}, \text{ EN} = 3.3 \text{V}, V_{\text{FB}} = 1 \text{V},$ no switching		2		mA
Shutdown Current	I <sub>SHDN</sub>	EN = 0V	-	2		uA
PVCC POR Threshold	V <sub>PVCCRTH</sub>	$V_{PVCC}$ rising, $T_A = 0^{\circ}$ C to 85°C	3.9	4.1	4.3	V
PVCC POR Hysteresis	V <sub>PVCCHYS</sub>			0.3		V
VREF Voltage Accuracy		$T_A = 0$ °C to 85°C	1.98	2	2.02	V
VREF Maximum Output Current			10			mA
Control Input: EN	•					
Logic Low Threshold		$T_A = 0^{\circ}C$ to $85^{\circ}C$			0.8	V
Logic High Threshold		$T_A = 0$ °C to 85°C	2.4			V
Internal Pull-down Current				10		uA
Reference Voltage						
REFIN Disable Threshold		$T_A = 0$ °C to 85°C			0.13	V
External Rererence Voltage Range	V <sub>REFIN</sub>		0.27		2	V
On Time						
One Shot Width	T <sub>on</sub>	$V_{OUT} = 1.1V, R_{TON} = 75k\Omega, V_{IN} = 12V$		280		ns
Minimum Off Time	T <sub>OFF_MIN</sub>			350		ns
USM Frequency						
USM Frequency	f <sub>usm</sub>	USM	25			kHz
PWM3 Output						
Output Low Voltage	V <sub>OL</sub>	$I_{SINK} = 4mA$ , $T_A = 0$ °C to 85°C			0.5	V
Output High Voltage	V <sub>OH</sub>	$I_{SRC} = 4\text{mA}, T_A = 0^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$	4.5			V
Error Amplifier						
Open Loop DC Gain	AO	Guaranteed by Design	70	80		dB
Gain-Bandwidth Product	GBW	$C_{LOAD} = 5pF$	30			MHz
Slew Rate	SR	Guaranteed by Design	3	6		V/us
Trans-conductance	GM	$R_{LOAD} = 20k\Omega$		1800		uA/V
Maximum Current (Source & Sink)	I <sub>COMP</sub>	V <sub>COMP</sub> = 1.6V	250	300		uA



# Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units	
Current Sense Amplifier							
Input Offset Voltage	V <sub>os</sub>		-1		1	mV	
Max Sourcing Current			100	7		uA	
ISENx Voltage		$R_{ISENx} = 5k\Omega$ for internal appliction, $T_A = 0$ °C to 85°C	25	30	35	mV	
FBRTN							
FBRTN Current	I <sub>FBRTN</sub>	EN = 3.3V, no switching			500	uA	
Soft Start			7	•			
Soft Start Period	T <sub>ss</sub>	From EN = high to PGOOD = high		1.4		ms	
PWMVID Buffer							
VID Input Low Level	V <sub>OL</sub>			1		V	
VID Input High Level	$V_{OH}$			2		V	
VID Tri-state Delay				100		ns	
REFADJ Output Low Voltage	V <sub>L</sub>	$I_{SINK} = 1 \text{mA}, T_A = 0^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$	0		0.05	V	
REFADJ Output High Voltage	V <sub>IH</sub>	$I_{SRC} = 1 \text{mA}, T_A = 0^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$	1.95		2	V	
VREFADJ Source Resistance	$R_{BF\_SRC}$	$I_{SRC} = 1 \text{mA}, T_A = 0^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$	10	20	30	Ω	
VREFADJ Sink Resistance	$R_{\rm BF\_SNK}$	$I_{SNK} = 1 \text{mA}, T_A = 0^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}$	10	20	30	Ω	
PSI				!			
	V <sub>PSI</sub>	Multi-phase CCM, $T_A = 0$ °C to 85°C	52			% of PVCC	
Dower Soving Input Threshold		USM, $T_A = 0^{\circ}C$ to $85^{\circ}C$	36		44	% of PVCC	
Power Saving Input Threshold		Single-phase FCCM, $T_A = 0^{\circ}C$ to 85°C	20		28	% of PVCC	
		PSM, $T_A = 0^{\circ}C$ to $85^{\circ}C$			12	% of PVCC	
Gate Drivers							
Upper Gate Source	$R_{UG\_SRC}$	$I_{UG} = -80 \text{mA}$		1	2	Ω	
Upper Gate Sink	R <sub>UG_SNK</sub>	$I_{UG} = 80 \text{mA}$		0.5	1	Ω	
Lower Gate Source	$R_{LG\_SRC}$	I <sub>LG</sub> = -80mA		1	2	Ω	
Lower Gate Sink	$R_{LG\_SNK}$	I <sub>LG</sub> = 80mA		0.4	0.8	Ω	
Dead Time	T <sub>DT</sub>			30		ns	
Internal Bootstrap Switch							
On Resistance	R <sub>ST</sub>	I <sub>F</sub> = 10mA		80		Ω	
Reverse Leakage Current	I <sub>ST</sub>	$V_{BOOTX} = 26V$		0.01	1.5	uA	



### **Electrical Characteristics**

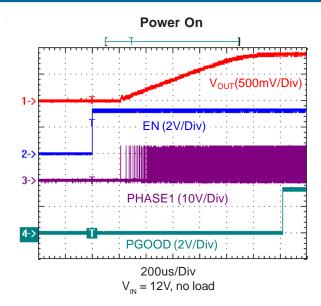
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Zero Current Detection Threshold						
Zero Current Threshold	V <sub>zc</sub>	GND-PHASE		2		mV
Protection			7/			
Short Circuit Protection Threshold Level	I <sub>ISENx</sub>	$R_{ISENx} = 5k\Omega$ , $T_A = 0^{\circ}C$ to $85^{\circ}C$	1	37.5		uA
OVP Threshold	V <sub>OVP</sub>	$V_{FB}/V_{REFIN}$ , $T_A = 0$ °C to 85°C	130		150	%
UVP Threshold	V <sub>UVP</sub>	$V_{FB}/V_{REFIN}$ , $T_A = 0$ °C to 85°C	45		55	%
OTP Threshold		$T_A = 0^{\circ}C$ to $85^{\circ}C$	150		170	οС
Temperature Monitor						
TALERT# Threshold Level	V <sub>TSNS</sub>	TALERT# high to low	33	35	37	% of VREF
TALERT# Hysteresis	V <sub>TSNS_HYS</sub>	TALERT# low to high hysteresis		7.5		% of VREF
Power Good Indicator						
Power Good Indicator		I <sub>SINK</sub> = 4mA			0.3	V

- **Note 1.** Stresses listed as the above *Absolute Maximum Ratings* may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.
- Note 2. Devices are ESD sensitive. Handling precaution recommended.
- **Note 3.**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^{\circ}$ C on a low effective thermal conductivity test board of JEDEC 51-3 thermal measurement standard.
- Note 4. The device is not guaranteed to function outside its operating conditions.





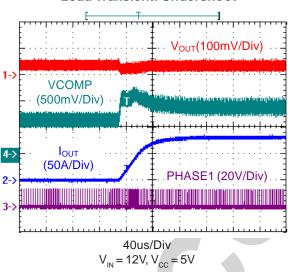
### **Typical Operation Characteristics**

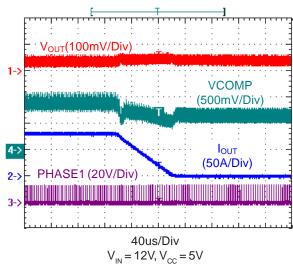


# **Power Off** V<sub>OUT</sub>(500mV/Div) EN (2V/Div) PHASE1 (10V/Div) 4-> PGOOD (2V/Div) 200us/Div $V_{IN} = 12V$ , no load



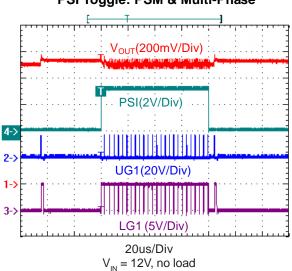


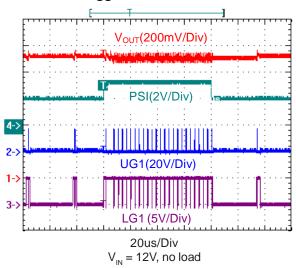




### PSI Toggle: PSM & Multi-Phase

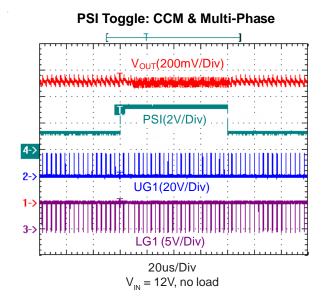
### PSI Toggle: USM & Multi-Phase

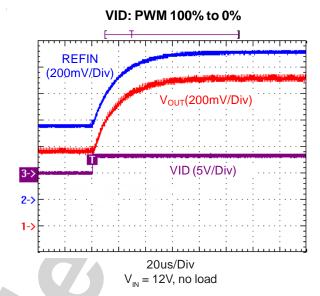


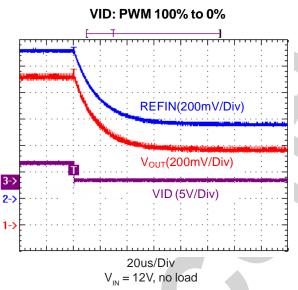


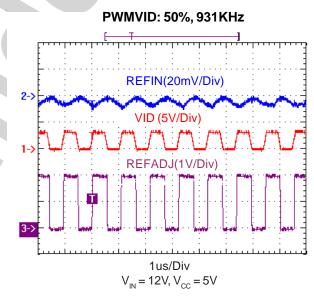


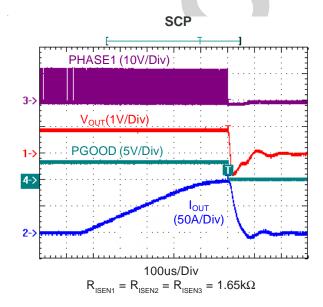
# **Typical Operation Characteristics**

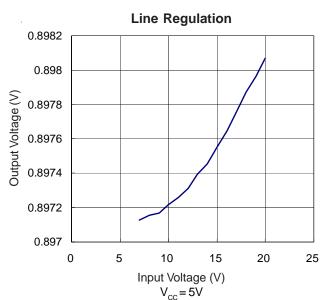






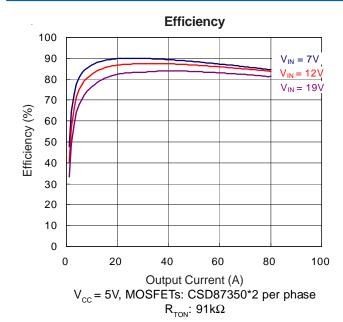








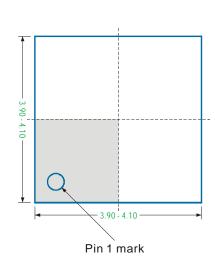
# **Typical Operation Characteristics**

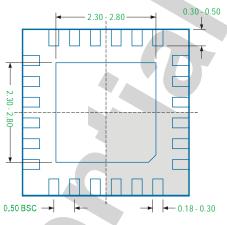




### **Package Information**

### VQFN4x4 - 24L





Bottom View - Exposed Pad



### Note

1. Package Outline Unit Description:

BSC: Basic. Represents theoretical exact dimension or dimension target

MIN: Minimum dimension specified.

MAX: Maximum dimension specified.

REF: Reference. Represents dimension for reference use only. This value is not a device specification.

TYP. Typical. Provided as a general value. This value is not a device specification.

- 2. Dimensions in Millimeters.
- 3. Drawing not to scale.
- 4. These dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm.



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